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FDN359BN

N-Channel Logic Level PowerTrench[™] MOSFET

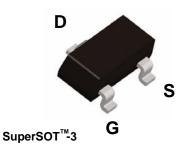
General Description

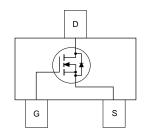
This N-Channel Logic Level MOSFET is produced using Fairchild's Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Features

- 2.7 A, 30 V. $R_{DS(ON)} = 0.046 \ \Omega \ @ \ V_{GS} = 10 \ V$ $R_{DS(ON)} = 0.060 \ \Omega \ @ \ V_{GS} = 4.5 \ V$
- Very fast switching speed.
- Low gate charge (5nC typical)
- High performance version of industry standard SOT-23 package. Identical pin out to SOT-23 with 30% higher power handling capability.





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Maximum Drain Current – Continuous	(Note 1a)	2.7	А
	– Pulsed		15	
P _D	Maximum Power Dissipation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T _J , T _{STG}	Operating and Storage Temperature Rang	је	-55 to +150	°C

Thermal Characteristics

R _{θJA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity	
359B	FDN359BN	7"	8mm	3000 units	

Symbol	Parameter	Test (Conditions	Min	Тур	Max	Units
Off Char	acteristics				ı	ı	l
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 V$,	I _D = 250 μA	30			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu A, R$	eferenced to 25°C		21		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V},$	$V_{GS} = 0 V$			1	μΑ
			$T_J = -55^{\circ}C$			10	μΑ
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V},$	$V_{DS} = 0 V$			±100	nA
On Char	acteristics (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I _D = 250 μA	1	1.8	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu A, R$	eferenced to 25°C		-4		mV/°C
$R_{\text{DS(on)}}$	Static Drain–Source On–Resistance	$V_{GS} = 10 \text{ V},$ $V_{GS} = 4.5 \text{ V},$ $V_{GS} = 10 \text{ V}, I_D$	$I_D = 2.7 \text{ A}$ $I_D = 2.4 \text{ A}$ $= 2.7 \text{ A}, T_J = 125^{\circ}\text{C}$		0.026 0.032 0.033	0.046 0.060 0.075	Ω
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V},$	V _{DS} = 5 V	15			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5V$,	I _D = 2.7 A		11		S
Dynamic	Characteristics						
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V},$	V _{GS} = 0 V,		485	650	pF
Coss	Output Capacitance	f = 1.0 MHz			105	140	pF
C _{rss}	Reverse Transfer Capacitance				65	100	pF
R _G	Gate Resistance	f = 1.0 MHz			1.8		Ω
Switchin	ng Characteristics (Note 2)						
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 15V$,	$I_D = 1 A$		7	14	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V},$	$R_{GEN} = 6 \Omega$		5	10	ns
t _{d(off)}	Turn-Off Delay Time	-			20	35	ns
t _f	Turn-Off Fall Time	1			2	4	ns
Q_g	Total Gate Charge	V _{DS} = 15 V,	$I_D = 2.7 A,$		5	7	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 5 V			1.3		nC
Q_{gd}	Gate-Drain Charge				1.8		nC

Electrical Characteristics

T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-Se	Drain-Source Diode Characteristics and Maximum Ratings					
Is	Maximum Continuous Drain-Source Diode Forward Current				0.42	Α
V _{SD}	Drain–Source Diode Forward $V_{GS} = 0 \text{ V}, I_S = 0.42 \text{ A}$ (Note 2) Voltage			0.7	1.2	V
trr	Diode Reverse Recovery Time IF = 2.7A, diF/dt = 100 A/µs			12	20	ns
Qrr	Diode Reverse Recovery Charge			3	5	nC

otes:

 R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² pad of 2 oz. copper.



b) 270°C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

Typical Characteristics

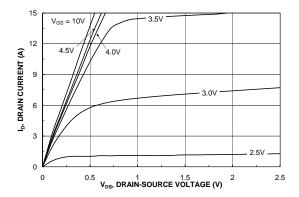
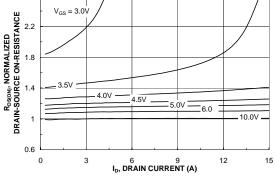


Figure 1. On-Region Characteristics.



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Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

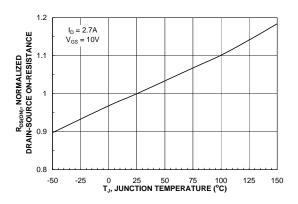


Figure 3. On-Resistance Variation with Temperature.

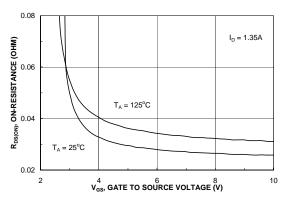


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

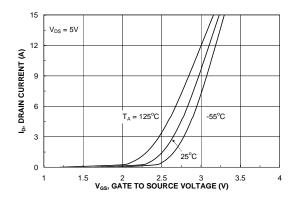


Figure 5. Transfer Characteristics.

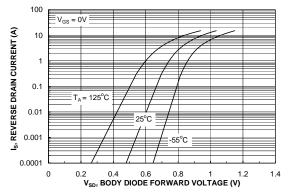
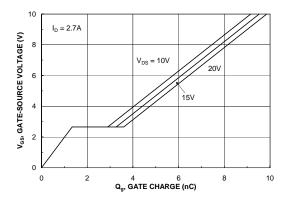


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



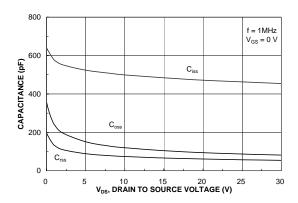
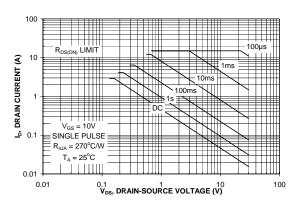


Figure 7. Gate Charge Characteristics.





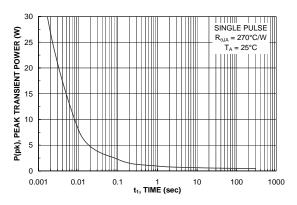


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

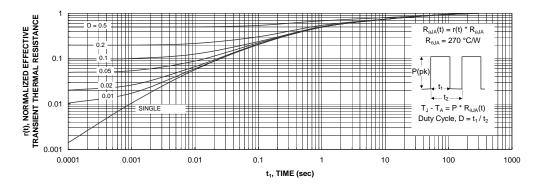


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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